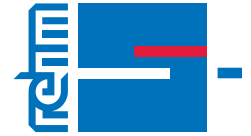


Advanced Reflow Soldering Seminar

Temperature Profiling and Troubleshooting



THERMAL SYSTEMS



September 29, 2026 in Timisoara, Romania

Today reflow soldering is still the most important connection technology for electronic assemblies. Our Advanced Reflow Soldering Seminar in Timisoara will focus on several important factors that influence the reflow soldering quality: What are the main aspects of an optimal soldering profile? How can you avoid common and special defect mechanisms? You can discuss your problems concerning reflow soldering with experts in this field. Rehm Thermal Systems invites you to broaden your horizon at this opportunity and welcomes you to Timisoara.

09:30 a.m.	Welcome and Introduction <i>Andreas Heltmann, Rehm Thermal Systems</i>	1:15 p.m.	Soldering With and Without Nitrogen > Advantages and disadvantages <i>Dr. Paul Wild, Rehm Thermal Systems</i>
09:45 a.m.	Novel Interconnect solutions > SLP, EMB, Cavity, Semi/RigidFlex and ZiC <i>Florian Amtmann, AT&S</i>	1:45 p.m.	New Trends in Soldering – Systems and Process Technology > Low-Temperature Soldering (LTS), > Formic Acid <i>Dr. Paul Wild, Rehm Thermal Systems</i>
10:45 a.m.	Temperature Profiling, Vacuum Reflow, and Void Reduction – Latest IEC Technical Reports > Measurement methods, tolerances, and acceptance criteria <i>Dr. Paul Wild, Rehm Thermal Systems</i>	2:15 p.m.	Coffee Break
11:15 a.m.	Coffee Break	2:45 p.m.	Troubleshooting > Whiskers and Black-Pad > Wicking and Graping > Voids <i>Dr. Paul Wild, Rehm Thermal Systems</i>
11:30 a.m.	Solder Paste Chemistry and its Behaviour during Reflow Soldering > Future Trends in Solder Pastes & Low-Temperature Soldering (LTS), Formic Acid <i>Cristian Tudor, Indium</i>	3:45 p.m.	Perfect maintenance – Perfect Soldering > Filters, heat exchangers cleaning, > Oven interior manual cleaning <i>Jaroslav Jalový, DCT</i>
12:30 p.m.	Lunch break	4:45 p.m.	End of seminar Time for discussions and Get-Together

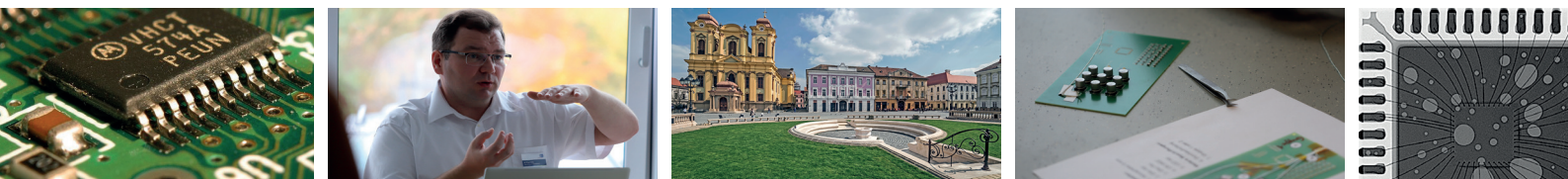
Attendance fees including beverage, lunch and seminar material

129,00 € per day >> registration **before** September 1, 2026

149,00 € per day >> registration **after** September 1, 2026

Register for both days and get an extra discount of 10% on the above attendance fee!

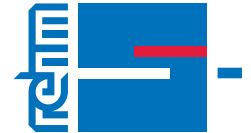
Subject to substantive adjustments



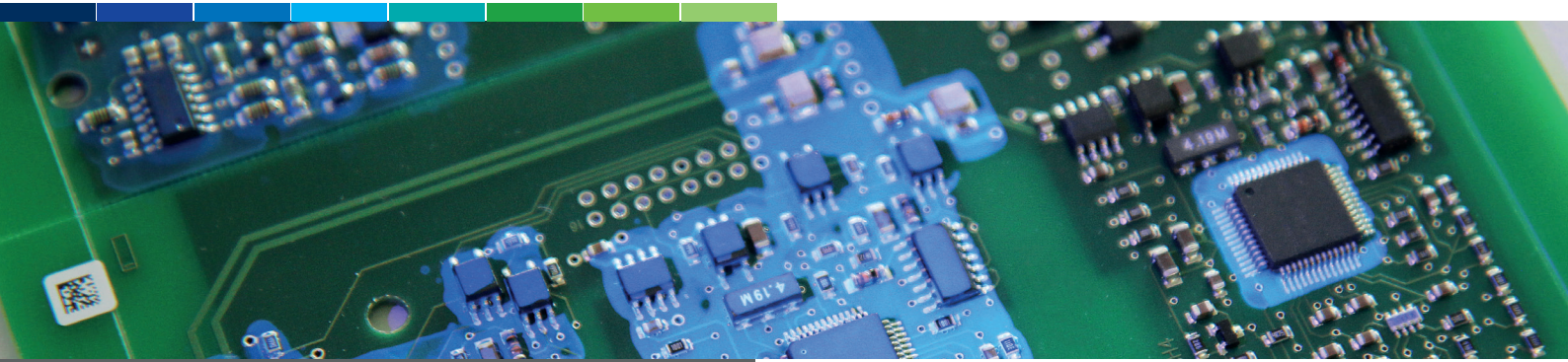
TECHNOLOGY ACADEMY
Advanced Reflow Soldering Seminar

Advanced Conformal Coating Seminar

Conformal Coating



THERMAL SYSTEMS



September 30, 2026 in Timisoara, Romania

How do you ensure sustainable PCB protection for your electronic components? The coating technology in the electronics industry continues to advance. The wide range of materials and application methods are specially adapted to the assembly to be produced. It is not easy not to lose the overview here. On the second day of our seminar, you will learn about the basics and the diversity of coating technology and smart communication in line through to failure analysis of your coated product.

09:30 a.m.	Welcome and Introduction <i>Andreas Heltmann, Rehm Thermal Systems</i> <i>Gianfranco Sinistra, Rehm Thermal Systems</i>	1:15 p.m.	Cleaning: Pro and Cons > Challenges, what if not <i>Jaroslav Jalový, DCT</i>
09:45 a.m.	Where Conformal Coating Meets the PCB > Material Interfaces and Surface Quality for a Reliable Protection <i>Jonatan Milione, NCAB</i>	2:00 p.m.	Failure Analysis > During the production process, On the product <i>Gianfranco Sinistra, Rehm Thermal Systems</i>
10:45 a.m.	Different materials > Conformal Coating Materials in Electronics: Chemistry groups and Selection Frameworks <i>Balint Gyorffy, HumiSeal</i>	2:45 p.m.	Coffee Break
11:15 a.m.	Coffee Break	3:15 p.m.	Workpiece Carrier > Process challenges, material and cleaning > Project management <i>Oliver Hagemes, Rösnick</i>
11:45 a.m.	Variety of Coating Technologies > Which material for which application? And How To do a easy program? <i>Gianfranco Sinistra, Rehm Thermal Systems</i>	4:00 p.m.	Line Connectivity >Smart Communications <i>Gianfranco Sinistra, Rehm Thermal Systems</i>
12:45 p.m.	Lunch Break	3.30 p.m.	End of Seminar Time for Discussions and Get-Together

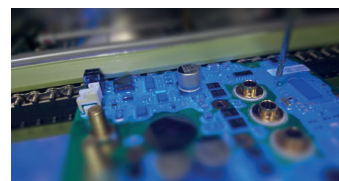
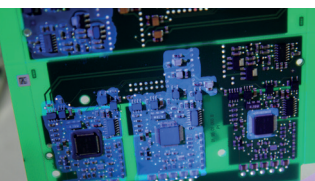
Attendance fees including beverage, lunch and seminar material

129,00 € per day >> registration **before** September 1, 2026

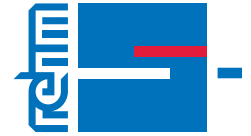
149,00 € per day >> registration **after** September 1, 2026

Register for both days and get an extra discount of 10% on the above attendance fee!

Subject to substantive adjustments



TECHNOLOGY ACADEMY
Advanced Reflow Soldering Seminar



THERMAL SYSTEMS

Registration to the Advanced Reflow Soldering and Conformal Coating Seminar in Timisoara



Your participation Sept. 29, 2026 Sept. 30, 2026

129,00 € per day >> registration **before** September 1, 2026

149,00 € per day >> registration **after** September 1, 2026

Register for both days and get an extra discount of 10% on the participation fee!

Subject to a minimum number of 20 participants

I will participate in the seminar with _____ person(s) in total.

Company: _____

Participant(s): _____

Address: _____

Post Code: _____ City: _____

Country: _____ Phone: _____

E-Mail: _____

Different billing address: _____

Contact person for invoice: _____
(Name and E-Mail)

VAT identification number: _____

- » Return by E-Mail: sales@rehm-group.com
- » Or register on our Website: www.rehm-group.com/en/news/dates

Location of the seminar is **HOTEL TIMISOARA, 300086 Marasesti Str. 1-3, Timisoara, Romania.**

If you need an accommodation you can book a room from our contingent with the keyword.

Keyword: **REHM2026 (only by e-mail)**

Mrs. Simona Andreica | E-Mail: office@hoteltimisoara.ro

Phone: +40 256 498 852 | Web: www.hoteltimisoara.ro

The price for one single room is 90 € (Business room) per night incl. breakfast.

